



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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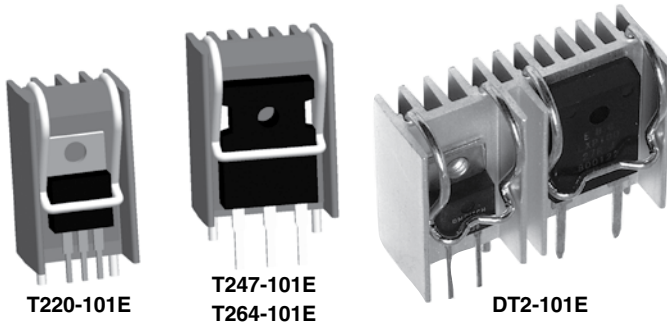
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W Series Heatsinks

For TO-220, TO-247, and TO-264 devices



The unique design (patent pending) of the W Series heat sinks combines a tin plated, solderable, integral spring clip with an extruded aluminum heat sink body for an all-in-one solution to through-hole mounting of TO-220, TO-247, and TO-264 packages. These self-aligning heat sinks feature solderable feet and an integrated clip with 13.2 (lbf) of force on the center of the device to enhance thermal performance.

FEATURES

- Reduced Assembly Cost: spring clip and auto-align feature makes fasteners and fixtures obsolete, along with stray metal filings from tapped holes
- Maximum Repeatability: clamping force of the spring clip is not degraded by repeated loading and unloading
- Maximum Heat Transfer per Unit Space: maximum surface area per unit volume and consistent mounting force reduces thermal resistance
- Maximum Resistance to Shock and Vibration: light weight, resilient spring clip locks the component in place and is highly resistant to shock and vibration
- Maximum Reliability: helps prevent short circuits by eliminating metal particles from thread tapping
- RoHS Compliant

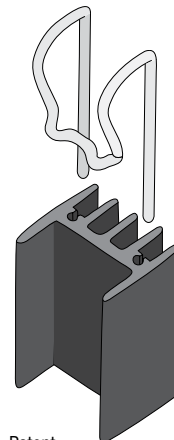
SERIES SPECIFICATIONS

Heatsink Part Number	For Package Type	Ohmite Resistor Series	Surface Area (in ²)	Weight	Thermal Resistance*
WA-T220-101E WV-T220-101E	TO-220	TBH25, TCH35	6.5	0.35 oz/10g	Rs-a=12°C/W Rs-a=13°C/W
WA-T247-101E WV-T247-101E	TO-247	TEH70, TEH100	8.4	0.42 oz/12g	Rs-a=11°C/W Rs-a=12°C/W
WA-T264-101E WV-T264-101E	TO-264	TFH85	8.4	0.42 oz/12g	Rs-a=11°C/W Rs-a=12°C/W
WA-DT2-101E WV-DT2-101E	TO-220 & TO-247	TBH25, TCH35, TEH70, TEH100	15.1	0.79 oz/22g	Rs-a=7°C/W Rs-a=8°C/W

*Natural convection at 10W heat dissipation

CHARACTERISTICS

Heat Sink	Aluminum alloy 6063-T5 or equivalent.
Spring Clip	Music wire, per ASTM A228
Pin	Solderable 100% tin over copper strike
Interface thermal resistance	for improvement, use thermal joint compound or 0.005 Grafoil (TGon 800 by Laird)
Interface electrical isolation	Sil-Pad 900S by Bergquist or equivalent
Mounting	Vertical thru-hole mount
Clip Force	13.2 lbf.



Patent Pending

(continued)

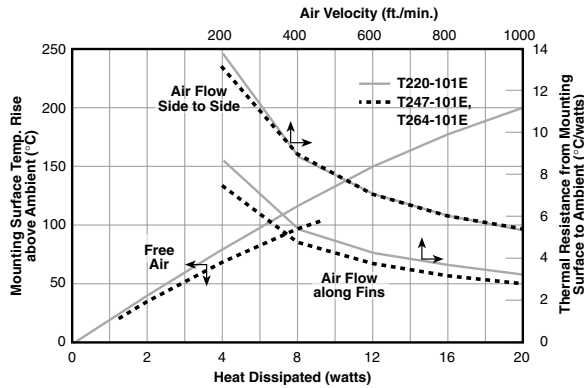
W Series Heatsinks

For TO-220, TO-247, and TO-264 devices

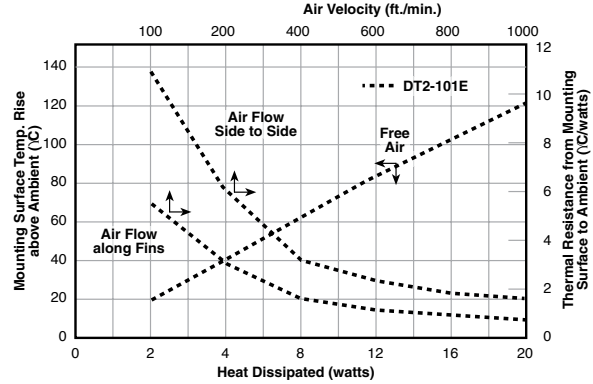
CHARACTERISTICS

Heat Dissipation

T220-101E, T247-101E and T264-101E

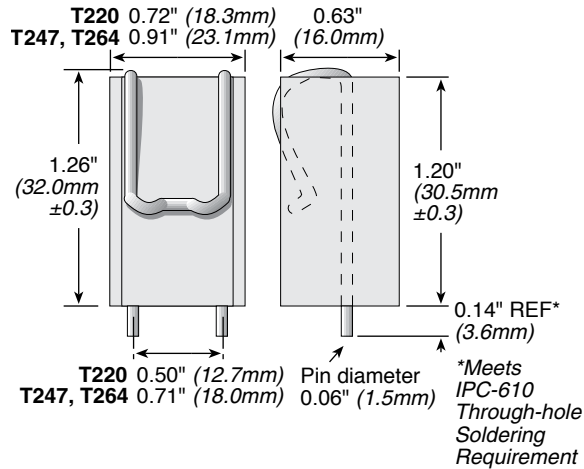


DT2-101E

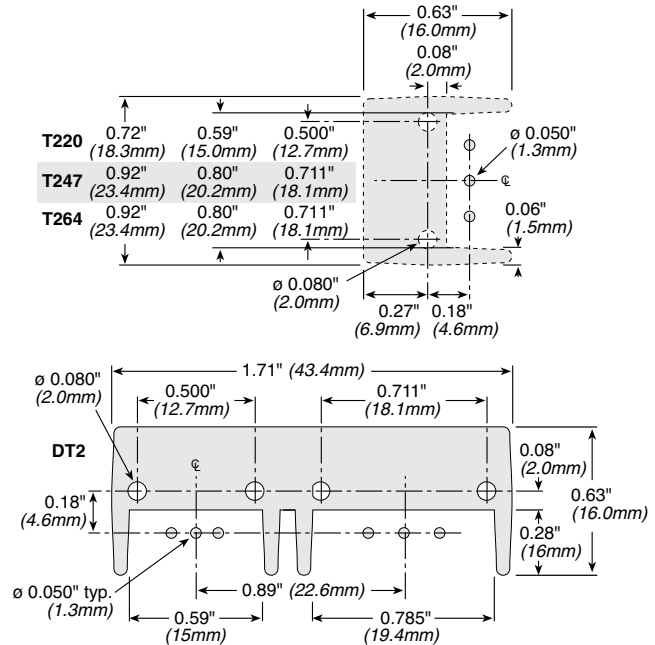


DIMENSIONS

(in./mm ±0.3mm)



Land pattern



ORDERING INFORMATION

W A - T 2 2 0 - 1 0 1 E

Series	Coating	Device size	Package modifier	RoHS Compliant
	A- Black Anodized V- degreased N- Alodine 1500 Clear			

Standard part numbers

WA-T220-101E
WV-T220-101E
WA-T247-101E
WV-T247-101E
WA-T264-101E
WV-T264-101E
WA-DT2-101E
WV-DT2-101E